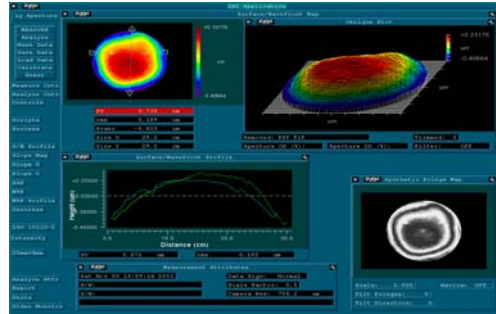


## Ultraprecise Vacuum Chuck

Combined state-of-the-art technology of flat machining and precise machining realizes stable and ultraprecise wafer clamping and decreases particle and scratch of wafer backside

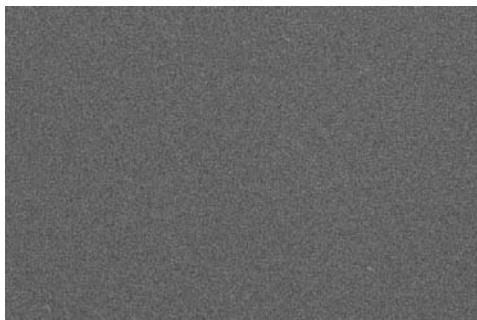


Data of Laser Interferometer for 12" Chuck

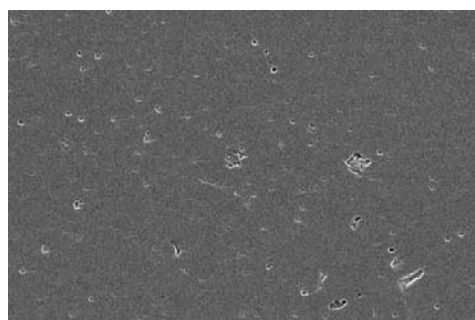
### 【Feature】

- High precision : Flatness 0.5μm, L/F 0.1μm
- Available material : Crystallized glass , SiC, Conductive Cerami
- Shape control : Tailored shape fits wafer
- Low particle : Porefree material and Special polishing

Surface microstructure of chuck material (SEM)



PoreFree



Alumina

### 【Application】

- Vacuum chuck of Wafer tester
- Fixture for processing machine

### 【Option】

- Our original cleaning technique enables advanced cleanliness.
- Cleaness of clamping surface after cleaning is maintained by our original package.
- Mapping data of particle on wafer backside can be measured by Particle Inspection

### Business headquarters

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